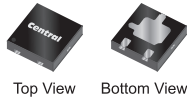
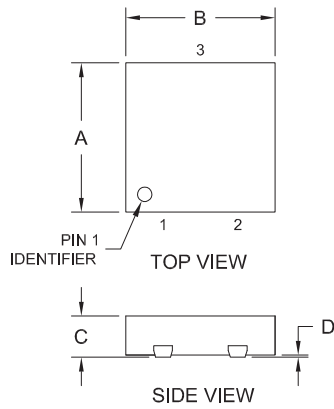


Package Details

TLM322S Case

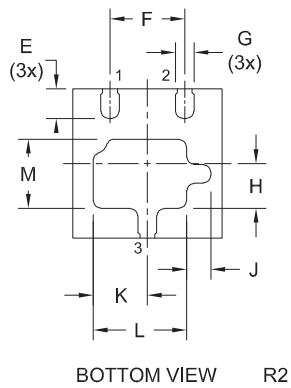


Mechanical Drawing



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.076	0.081	1.95	2.05
B	0.076	0.081	1.95	2.05
C	0.019	0.024	0.50	0.60
D	0.000	0.002	0.00	0.05
E	0.011	0.020	0.30	0.50
F	0.039		1.00	
G	0.007	0.012	0.18	0.30
H	0.017	0.028	0.45	0.70
J	0.008	0.017	0.22	0.43
K	0.024	0.033	0.62	0.83
L	0.043	0.054	1.10	1.35
M	0.030	0.041	0.77	1.03

TLM322S (REV:R2)



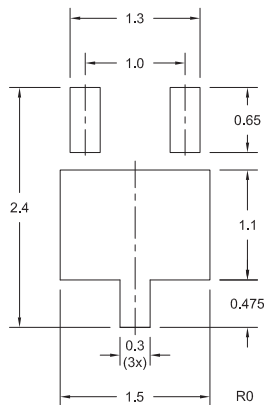
Part Marking:

2-3 Character Alpha/Numeric Code

Lead Code:

Reference individual device datasheet.

Mounting Pad Geometry (Dimensions in mm)



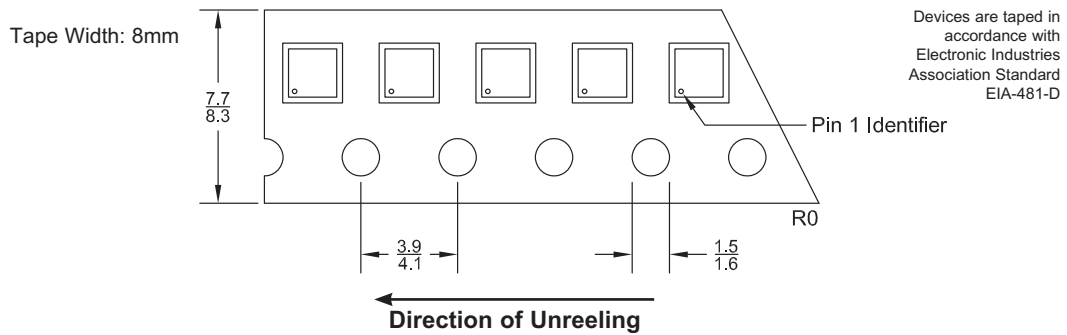
R1 (26-November 2013)

Package Details

TLM322S Case



Tape Dimensions and Orientation (Dimensions in mm)



Packaging Base

7" Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
 Central Part Number, Customer Part Number, Purchase Order Number,
 Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	27,000	9x9x5	23x23x13	4	2
	17	51,000	9x9x9	23x23x23	7	4
	40	120,000	21x9x9	53x23x23	14	7
	108	324,000	27x9x17	69x23x43	39	18

Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (26-November 2013)

Material Composition Specification

TLM322S Case



Top View Bottom View

Device average mass **6.0 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.167%	0.07	Si	7440-21-3	1.167%	0.07	11,667
bond wire	gold	0.5%	0.03	Au	7440-57-5	0.5%	0.03	5,000
leadframe	Cu alloy	24.5%	1.47	Cu	7440-50-8	23.167%	1.39	231,667
				Ni	7440-02-0	0.867%	0.052	8,667
				Ag	7440-22-4	0.233%	0.014	2,333
				Zn	7440-66-6	0.117%	0.007	1,167
				Si	7440-31-5	0.117%	0.007	1,167
die attach	silver epoxy	0.3%	0.018	epoxy resin	Proprietary	0.067%	0.004	667
				Ag	7440-22-4	0.233%	0.014	2,333
encapsulation*	EMC GREEN	71.066%	4.264	silica (fused)	60676-86-0	66.583%	3.995	665,833
				epoxy resin	29690-82-2	2.133%	0.128	21,333
				phenol resin	9003-35-4	2.133%	0.128	21,333
				carbon black	1333-86-4	0.217%	0.013	2,167
plating	matte tin	2.467%	0.148	Sn	7440-31-5	2.467%	0.148	24,667

*EMC GREEN molding compound is Halogen Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-January 2012)